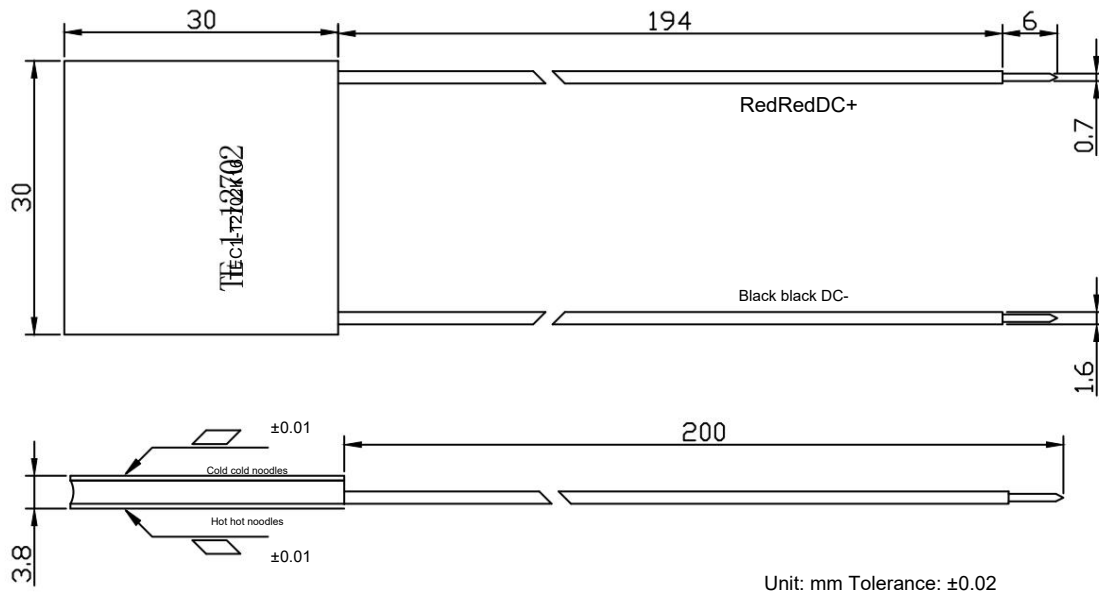


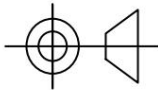
Semiconductor refrigeration chip specifications

TES1-12702

1. Dimensions



2. Performance indicators

Product	Model	TES1-12702	Dimensions	Size	30x30x3.8mm	
Maximum voltage	Vmax	DC15.2V	Internal resistance	Impe	5.46Ω	
Maximum current	Imax	2.0A	Solder type	Solder	Bi67+Sn33	
Maximum temperature difference	DTmax	60℃	Packaging material	materia	96% alumina+CU2	
Input power	Wmax	30W	Sealing material	Seal up	704 silicone rubber	
Cooling capacity	Cool	18W	Lead specifications Wire standard	Wire gauge	length	terminal
Maximum temperature resistance	Kmax	≤180℃		UL1007	+Red 200	NO
				22AGW	-Black 200	
Thermoelectric Cooler			Making orders	Name	Huang Dong	
			Update date	Date	2023-01-09	